National Semiconductor

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74LCX574
Low Voltage Octal D-Type Flip-Flop with 5V Tolerant Inputs and Outputs

General Description

The 'LCX574 is a high-speed, low power octal flip-flop with a buffered common Clock (CP) and a buffered common Output Enable ($\overline{OE}$). The information presented to the D inputs is stored in the flip-flops on the LOW-to-HIGH Clock (CP) transition.

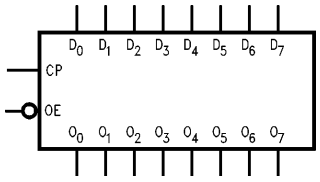
The 'LCX574 is functionally identical to the LCX374 except for the pinouts.

The 'LCX574 is designed for low voltage (3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment. The 'LCX574 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant inputs and outputs
- 7.5 ns t_{PD} max, 10 μA I_{CCQ} max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal
- 2.0V–3.6V V_{CC} supply operation
- $\pm$24 mA output drive
- Implements patented Quiet Series™ noise/EMI reduction circuitry
- Functionally compatible with 74 series 574
- Latch-up performance exceeds 500 mA
- ESD performance:
  Human body model > 2000V
  Machine model > 200V

Logic Symbols



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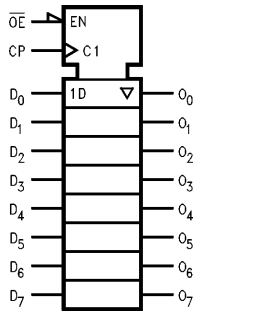
IEEE/IEC



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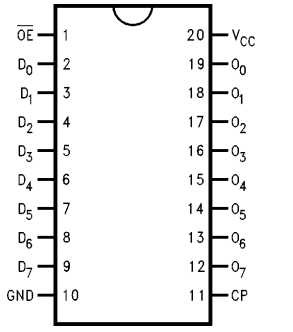
Pin Names	Description
D_0–D_7	Data Inputs
CP	Clock Pulse Input
$\overline{OE}$	TRI-STATE® Output Enable Input
O_0–O_7	TRI-STATE Outputs

Connection Diagram

Pin Assignment for SOIC, SSOP and TSSOP



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	SOIC JEDEC	SOIC EIAJ	SSOP Type II	TSSOP JEDEC
Order Number	74LCX574WM 74LCX574WMX	74LCX574SJ 74LCX574SJX	74LCX574MSA 74LCX574MSAX	74LCX574MTC 74LCX574MTCX
See NS Package Number	M20B	M20D	MSA20	MTC20

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Functional Description

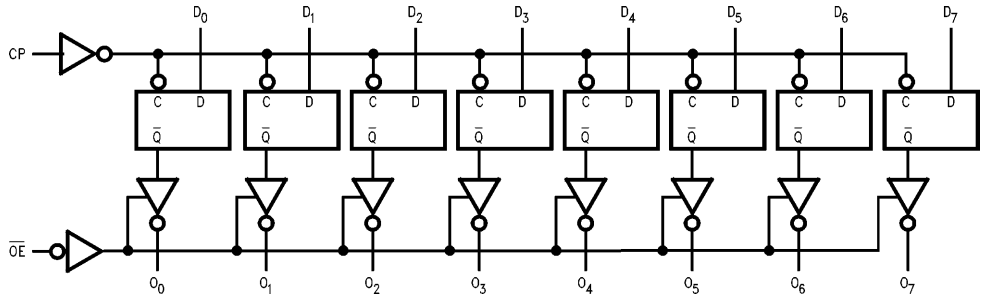
The 'LCX574 consists of eight edge-triggered flip-flops with individual D-type inputs and TRI-STATE true outputs. The buffered clock and buffered Output Enable are common to all flip-flops. The eight flip-flops will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP) transition. With the Output Enable ($\overline{OE}$) LOW, the contents of the eight flip-flops are available at the outputs. When $\overline{OE}$ is HIGH, the outputs go to the high impedance state. Operation of the $\overline{OE}$ input does not affect the state of the flip-flops.

Function Table

Inputs			Internal	Outputs	Function
$\overline{OE}$	CP	D	Q	O_N	
H	H	L	NC	Z	Hold
H	H	H	NC	Z	Hold
H	⌐	L	L	Z	Load
H	⌐	H	H	Z	Load
L	⌐	L	L	L	Data Available
L	⌐	H	H	H	Data Available
L	H	L	NC	NC	No Change in Data
L	H	H	NC	NC	No Change in Data

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance
⌐ = LOW-to-HIGH Transition
NC = No Change

Logic Diagram



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Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Symbol	Parameter	Value	Conditions	Units
V_{CC}	Supply Voltage	−0.5 to +7.0		V
V_I	DC Input Voltage	−0.5 to +7.0		V
V_O	DC Output Voltage	−0.5 to +7.0	Output in TRI-STATE	V
		−0.5 to V_{CC} + 0.5	Output in High or Low State (Note 2)	V
I_{IK}	DC Input Diode Current	−50	V_I < GND	mA
I_{OK}	DC Output Diode Current	−50 +50	V_O < GND V_O > V_{CC}	mA
I_O	DC Output Source/Sink Current	±50		mA
I_{CC}	DC Supply Current per Supply Pin	±100		mA
I_{GND}	DC Ground Current per Ground Pin	±100		mA
T_{STG}	Storage Temperature	−65 to +150		°C

Note 1: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the ''Electrical Characteristics'' table are not guaranteed at the Absolute Maximum Ratings. The ''Recommended Operating Conditions'' table will define the conditions for actual device operation.

Note 2: I_O Absolute Maximum Rating must be observed.

Recommended Operating Conditions

Symbol	Parameter		Min	Max	Units
V_{CC}	Supply Voltage	Operating Data Retention	2.0 1.5	3.6 3.6	V
V_I	Input Voltage		0	5.5	V
V_O	Output Voltage	HIGH or LOW State TRI-STATE	0 0	V_{CC} 5.5	V
I_{OH}/I_{OL}	Output Current	V_{CC} = 3.0V−3.6V V_{CC} = 2.7V		±24 ±12	mA
(T_A)	Free-Air Operating Temperature		−40	85	°C
$\Delta t/\Delta V$	Input Edge Rate, V_{IN} = 0.8V–2.0V, V_{CC} = 3.0V		0	10	ns/V

DC Electrical Characteristics

Symbol	Parameter	Conditions	V_{CC} (V)	T_A = −40°C to +85°C		Units
				Min	Max	
V_{IH}	HIGH Level Input Voltage		2.7–3.6	2.0		V
V_{IL}	LOW Level Input Voltage		2.7–3.6		0.8	V
V_{OH}	HIGH Level Output Voltage	I_{OH} = −100 μA	2.7–3.6	V_{CC} − 0.2		V
		I_{OH} = −12 mA	2.7	2.2		V
		I_{OH} = −18 mA	3.0	2.4		V
		I_{OH} = −24 mA	3.0	2.2		V
V_{OL}	LOW Level Output Voltage	I_{OL} = 100 μA	2.7–3.6		0.2	V
		I_{OL} = 12 mA	2.7		0.4	V
		I_{OL} = 16 mA	3.0		0.4	V
		I_{OL} = 24 mA	3.0		0.55	V
I_I	Input Leakage Current	0 ≤ V_I ≤ 5.5V	2.7–3.6		±5.0	μA
I_{OZ}	TRI-STATE Output Leakage	0 ≤ V_O ≤ 5.5V V_I = V_{IH} or V_{IL}	2.7–3.6		±5.0	μA
I_{OFF}	Power-Off Leakage Current	V_I or V_O = 5.5V	0		10	μA
I_{CC}	Quiescent Supply Current	V_I = V_{CC} or GND	2.7–3.6		10	μA
		3.6V ≤ V_I, V_O ≤ 5.5V	2.7–3.6		±10	μA
ΔI_{CC}	Increase in I_{CC} per Input	V_{IH} = V_{CC} −0.6V	2.7–3.6		500	μA

AC Electrical Characteristics

Symbol	Parameter	$T_A = -40°C$ to $+85°C$				Units
		$V_{CC} = 3.3V \pm 0.3V$		$V_{CC} = 2.7V$		
		Min	Max	Min	Max	
f_{MAX}	Maximum Clock Frequency	150				MHz
t_{PHL} t_{PLH}	Propagation Delay CP to O_n	1.5 1.5	8.5 8.5	1.5 1.5	9.5 9.5	ns
t_{PZL} t_{PZH}	Output Enable Time	1.5 1.5	8.5 8.5	1.5 1.5	9.5 9.5	ns
t_{PLZ} t_{PHZ}	Output Disable Time	1.5 1.5	6.5 6.5	1.5 1.5	7.0 7.0	ns
t_S	Setup Time	2.5		2.5		ns
t_H	Hold Time	1.5		1.5		ns
t_W	Pulse Width	3.3		3.3		ns
t_{OSHL} t_{OSLH}	Output to Output Skew (Note 3)		1.0 1.0			ns

Note 3: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH to LOW (t_{OSHL}) or LOW to HIGH (t_{OSLH}).

Dynamic Switching Characteristics

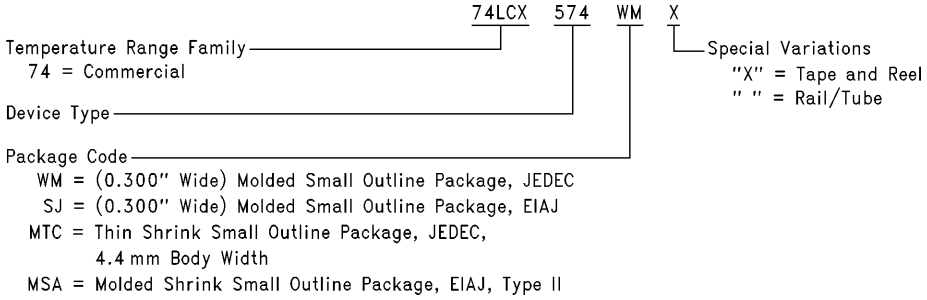
Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = 25°C$ Typical	Units
V_{OLP}	Quiet Output Dynamic Peak V_{OL}	$C_L = 50$ pF, $V_{IH} = 3.3V$, $V_{IL} = 0V$	3.3	0.8	V
V_{OLV}	Quiet Output Dynamic Valley V_{OL}	$C_L = 50$ pF, $V_{IH} = 3.3V$, $V_{IL} = 0V$	3.3	−0.8	V

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C_{IN}	Input Capacitance	V_{CC} = Open, $V_I = 0V$ or V_{CC}	7	pF
C_{OUT}	Output Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	8	pF
C_{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}, F = 10 MHz	25	pF

74LCX574 Ordering Information

The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:



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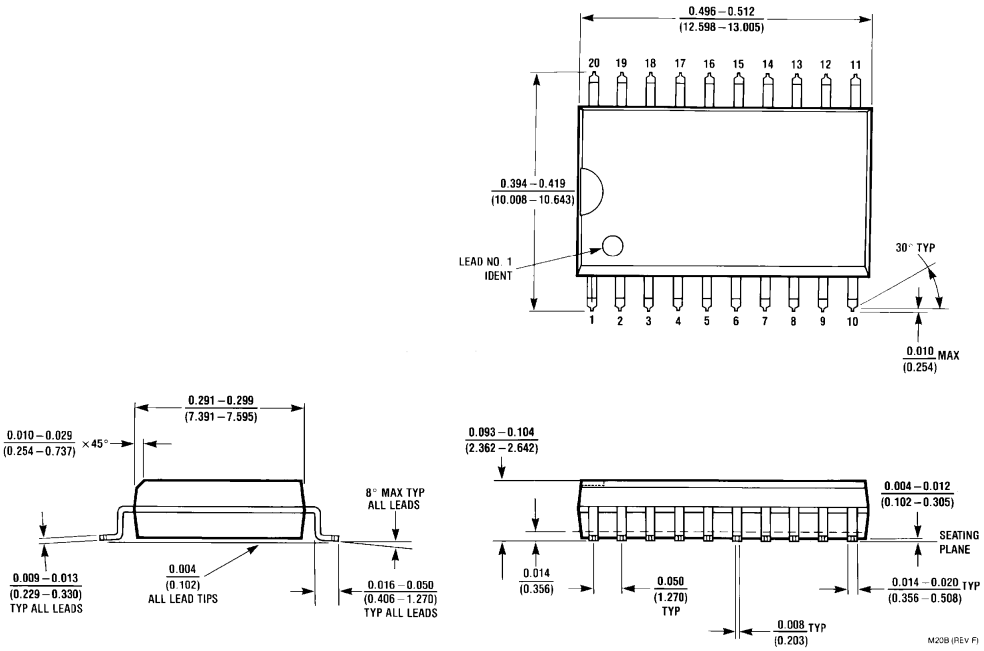
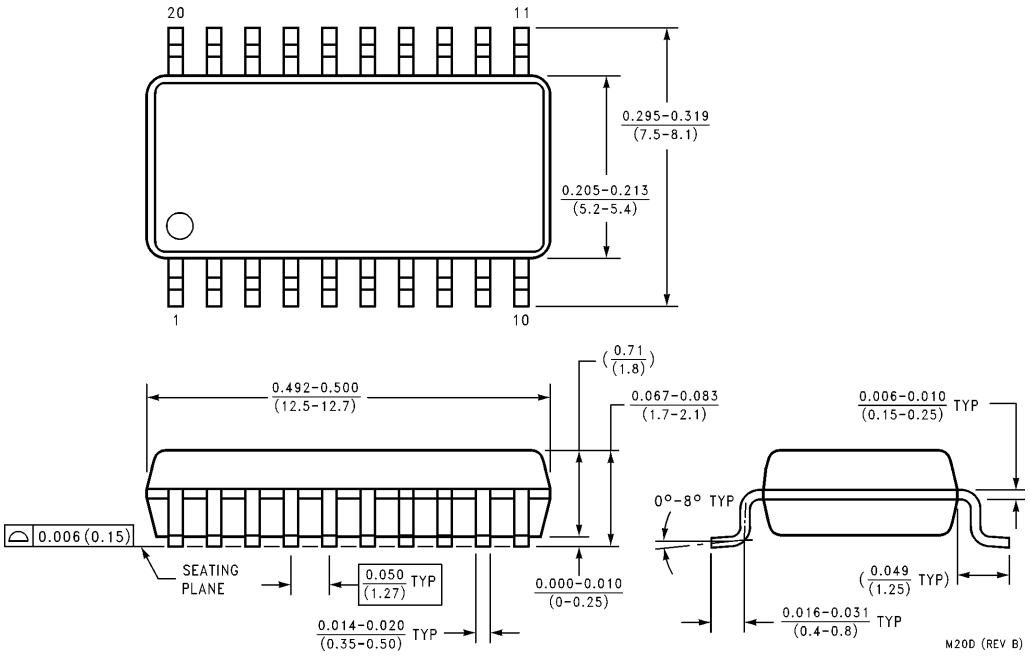
Physical Dimensions inches (millimeters) unless otherwise noted



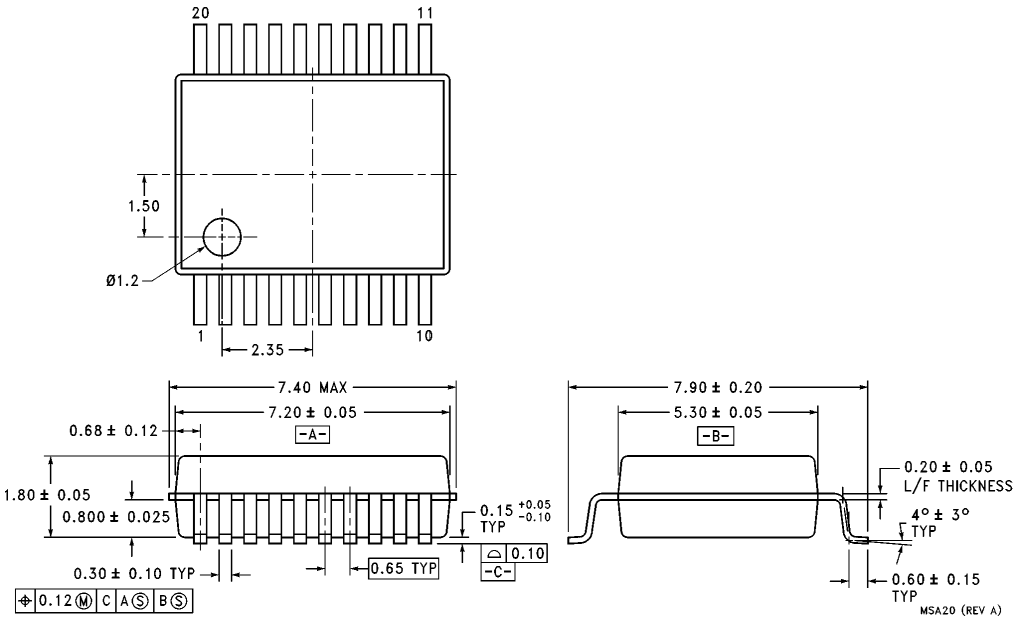
20-Lead (0.300″ Wide) Molded Small Outline Package, JEDEC
Order Number 74LCX574WM or 74LCX574WMX
NS Package Number M20B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



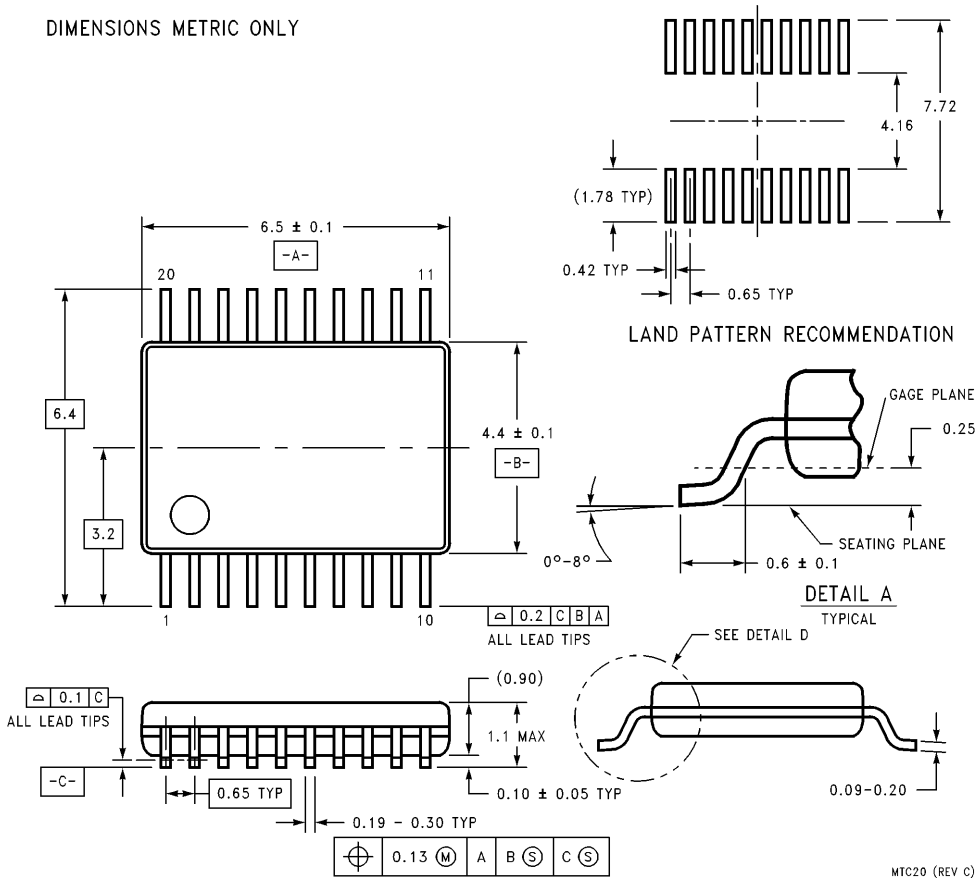
20-Lead (0.300″ Wide) Molded Small Outline Package, EIAJ
Order Number 74LCX574SJ or 74LCX574SJX
NS Package Number M20D

Physical Dimensions All dimensions are in millimeters (Continued)



20-Lead Molded Shrink Small Outline Package, EIAJ, Type II
Order Number 74LCX574MSA or 74LCX574MSAX
NS Package Number MSA20

Physical Dimensions All dimensions are in millimeters (Continued)



20-Lead Thin Shrink Small Outline Package, JEDEC
Order Number 74LCX574MTC or 74LCX574MTCX
NS Package Number MTC20

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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